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Field Device Integration (FDI®) – Part 4: FDI Packages

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CONTENTS

FOREWORD 8
~~INTRODUCTION~~ .....
1 Scope 11
2 Normative references 11
3 Terms, definitions, abbreviated terms and ~~conventions~~ acronyms 12
3.1 Terms and definitions 13
3.2 Abbreviated terms and acronyms 14
3.3 Conventions 14
4 FDI® Package Model 14
4.1 Overview 14
4.2 FDI® Package Elements 15
4.2.1 Package Catalog 15
4.2.2 Package Feature Table 15
4.2.3 Feature Unit Conversion 16
4.2.4 Electronic Device Description 15
4.2.5 User Interface Plug-in 16
4.2.6 Attachment 18
4.3 FDI® Package Types 18
4.3.1 FDI® Device Package 18
4.3.2 FDI® Communication Package 19
4.3.3 FDI® UIP Package 19
4.3.4 FDI® Profile Package 20
5 FDI® Package implementation 21
5.1 Packaging technology 21
5.2 Use of Open Packaging Conventions 21
5.2.1 Unknown parts 21
5.2.2 Invalid parts 22
5.2.3 Unknown relationships 22
5.2.4 Interleaving 22
5.2.5 Core properties 22
5.2.6 Thumbnails 22
5.2.7 Digital Signatures 22
5.3 FDI® Package parts 22
5.3.1 Package Catalog 22
5.3.2 Package Feature Table 23
5.3.3 Electronic Device Description 23
5.3.4 User Interface Plug-in 24
5.3.5 Attachments 27
6 FDI® Package versioning 30
6.1 Version scheme 30
6.2 Versioned elements 31
6.3 Version hierarchy 31
6.4 UIP compatibility 33
7 Digital Signatures and FDI® Registration Certificates 34
7.1 Signed elements and certification documents 34
7.2 Signing mechanism 35

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(https://standards.iteh.ai)
Document Preview
IEC 62769-4:2023
https://standards.iteh.ai/catalog/standards/iec/e00efb84-3e82-4c38-be11-c745c93b3155/iec-62769-4-2023

7.3 FDI® Package Originator, FDI® Registration Authority 36
7.4 FDI® Host behaviour 36
Annex A (normative) File name conventions 37
A.1 Identification 37
A.2 FDI® Package filename convention 37
Annex B (informative) FDI® Package creation 39
B.1 General 39
B.2 Tools and components 39
B.2.1 Overview 39
B.2.2 FDI® Reference Implementation/Common EDD Engine 39
B.2.3 FDI® Package IDE 39
B.2.4 FDI® Device Package Conformance Test Tool 39
B.3 Development 39
B.3.1 FDI® Package core development 39
B.3.2 User Interface Plug-in development 40
B.3.3 FDI® Package Attachment development 40
B.3.4 FDI® Package binding and packaging 40
B.3.5 Conformance Test 41
Annex C (informative) FDI® Package deployment 42
C.1 General 42
C.2 Scenarios 42
C.2.1 FDI® Package deployment to PC based client/server systems 42
C.2.2 FDI® Package deployment to an FDI® standalone system 43
Annex D (informative) Example 45
D.1 General 45
D.2 Open Packaging Conventions 45
D.2.1 Overview 45
D.2.2 Parts 45
D.2.3 Relationships 46
D.2.4 OPC Core features 46
D.2.5 OPC additional features 47
D.3 Creation and handling of FDI® Packages 48
D.4 FDI® Device Package example 48
D.4.1 Overview 48
D.4.2 User Interface Plug-in 53
D.4.3 EDD reference to UIP 55
D.4.4 FDI® Registration Certificate 56
Annex E (normative) FDI® Package Catalog XML Schema 57
E.1 Target Namespace 57
E.2 Catalog 57
E.3 ClassificationIdT 57
E.4 CommunicationProfileT 57
E.5 CommunicationRoleT 57
E.6 CommunicationServerT 58
E.7 DeviceTypeT 58
E.8 FDIRegistrationCert 59
E.9 FDIRegistrationCertT 59
E.10 InterfaceT 60

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Document Preview
IEC 62769-4:2023
https://standards.iteh.ai/catalog/standards/iec/e00ef084-3e82-4c38-be11-c745c93b3155/iec-62769-4-2023

E.11 ListOfCommunicationProfilesT 61
E.12 ListOfDeviceImagesT 61
E.13 ListOfDeviceTypesT 62
E.14 ListOfDocumentsT 62
E.15 ListOfInterfacesT 63
E.16 ListOfLocalizedStringsT 63
E.17 ListOfProtocolSupportFilesT 64
E.18 ListOfRegDeviceTypesT 64
E.19 ListOfRegistrationsT 64
E.20 ListOfSupportedDeviceRevisionsT 65
E.21 ListOfSupportedUipsT 65
E.22 ListOfUipVariantsT 66
E.23 LocalizedStringT 66
E.24 PackageT 66
E.25 PackageTypeT 67
E.26 PlatformT 68
E.27 RegDeviceTypeT 68
E.28 RegistrationT 69
E.29 RelationshipIdT 69
E.30 String256T 70
E.31 SupportedUipT 70
E.32 UipCatalog 70
E.33 UipStyleT 71
E.34 UipT 71
E.35 UipVariantT 72
E.36 UuidT 73
E.37 VersionSupportedT 73
E.38 VersionT 73
Annex F (normative) Communication protocol specific profiles 74
Annex G (informative) FDI® Package life-cycle use cases 75
G.1 New device type 75
G.2 Replacement of device 75
G.3 Firmware enhancements 75
G.4 FDI® Package life-cycle polices 76
G.5 FDI® Package update 76
G.6 FDI® Package upgrade 76
G.7 FDI® Package replacement/exchange 76
G.8 FDI® Package uninstallation 77
Annex H (normative) Health status Method 78
H.1 Background 78
H.2 Device health status model 78
H.3 Standard EDD Method signature 78
H.4 Performance considerations 79
Annex I (normative) Modular devices 80
I.1 Concept 80
I.2 EDDL usage profile 80
I.3 Processing recommendations 81
I.3.1 Monolithic device with device variants 81

iTeh Standards
(https://standards.iteh.ai)
Document Preview
IEC 62769-4:2023
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I.3.2 Remote IOs 81
I.3.3 How to identify the top level topology element 81
I.3.4 Packaging details example 81
Annex J (normative) FDI® Communication Packages for FDI® Communication Server 83
J.1 General 83
J.2 Protocol Support File 83
J.3 CommunicationProfile definition 83
J.4 Profile Device 83
J.5 Protocol version information 83
J.6 Associating a Package with an FDI® Communication Server 83
J.7 Handling of Catalog elements 83
J.8 Example 84
Annex K (normative) FDI® Profile for EDDs 85
K.1 Overview 85
K.2 Entry point to online handling 85
K.3 Entry point to offline handling 85
K.4 Non-interactive upload and download 85
K.5 Interactive download 85
K.6 Interactive upload 85
K.7 Initial data set 85
K.8 Method GetHealthStatus 86
K.9 Actions 86
K.9.1 Pre- and Post-Read Actions 86
K.9.2 Pre- and Post-Write Actions 86
K.9.3 Refresh Actions on Variables 86
K.9.4 Actions on BIT_ENUMERATION 86
K.10 Shared files 86
Annex L (normative) FDI® Package Documentation Catalog Schema 87
L.1 Target namespace 87
L.2 ListOfDocumentMetadataT 87
L.3 DocumentMetadataT 87
Annex M (normative) FDI® Package Feature Table Schema 89
M.1 Target namespace 89
M.2 FeatureTableT 89
M.3 Feature 89
M.4 FeatureProvidedbyPackage 89
M.5 UnitConversion 90
Bibliography 91

Figure 1 – FDI® architecture diagram 11
Figure 2 – FDI® Package Model 14
Figure 3 – Architectural mapping 15
Figure 4 – User Interface Plug-in Reference Model 17
Figure 5 – Multiple FDI® Packages referencing a common UIP 18
Figure 6 – FDI® Device Package 18
Figure 7 – FDI® Communication Package 19
Figure 8 – FDI® UIP Package 20

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IEC 62769-4:2023

Figure 9 – FDI® Profile Package 20
Figure 10 – Device Function and Parameter sets (type and profile specific) 21
Figure 11 – Catalog Element 23
Figure 12 – User Interface Plug-in 25
Figure 13 – UIP Catalog 26
Figure 14 – FDI® Registration Certificate 30
Figure 15 – Version hierarchy 32
Figure 16 – UIP version support concept 34
Figure 17 – FDI® Package signing 35
Figure B.1 – Tools used for FDI® Package development 40
Figure D.1 – Parts and relationships in a package 45
Figure D.2 – Creating an FDI® Package with the content files 48
Figure D.3 – FDI® Device Package example 49
Figure D.4 – User Interface Plug-in example (fancytrend.uip) 53
Figure I.1 – Modular device's package 80

Table 1 – UIP Platform Capabilities 17
Table 2 – Package Catalog part 23
Table 3 – Package Feature Table part 24
Table 4 – EDD part 24
Table 5 – User Interface Plug-in part 25
Table 6 – UIP Catalog part 27
Table 7 – UIP Variant part 27
Table 8 – Image part 28
Table 9 – Documentation part 28
Table 10 – Documentation Catalog part 28
Table 11 – Protocol Support File part 29
Table 12 – FDI® Registration Certificate part 29
Table 13 – Versioned elements 31
Table 14 – Influence on FDI® Package version 32
Table A.1 – FDI® Package Naming Convention 38
Table D.1 – Examples of standard MIME media types that can be used in FDI® Packages 47
Table D.2 – Examples of FDI®-custom MIME media types that can be used in FDI® Packages 47
Table E.1 – Enumerations of CommunicationRoleT 58
Table E.2 – Elements of CommunicationServerT 58
Table E.3 – Elements of DeviceTypeT 59
Table E.4 – Elements of FDIRegistrationCertT 60
Table E.5 – Elements of InterfaceT 61
Table E.6 – Elements of ListOfCommunicationProfilesT 61
Table E.7 – Elements of ListOfDeviceImagesT 62
Table E.8 – Elements of ListOfDeviceTypesT 62
Table E.9 – Elements of ListOfDocumentsT 63

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Document Preview
IEC 62769-4:2023
https://standards.iteh.ai/catalog/standards/iec/e00ef584-3e82-4c38-be11-c745c93b3155/iec-62769-4-2023

Table E.10 – Elements of ListOfInterfacesT 63
Table E.11 – Elements of ListOfLocalizedStringsT 63
Table E.12 – Elements of ListOfProtocolSupportFilesT 64
Table E.13 – Elements of ListOfRegDeviceTypesT 64
Table E.14 – Elements of ListOfRegistrationsT 65
Table E.15 – Elements of ListOfSupportedDeviceRevisionsT 65
Table E.16 – Elements of ListOfSupportedUipsT 65
Table E.17 – Elements of ListOfUipVariantsT 66
Table E.18 – Attributes of LocalizedStringT 66
Table E.19 – Elements of PackageT 67
Table E.20 – Enumerations of PackageTypeT 68
Table E.21 – Enumerations of PlatformT 68
Table E.22 – Elements of RegDeviceTypeT 69
Table E.23 – Elements of RegistrationT 69
Table E.24 – Elements of SupportedUipT 70
Table E.25 – Enumerations of UipStyleT 71
Table E.26 – Elements of UipT 72
Table E.27 – Elements of UipVariantT 72
Table F.1 – Communication protocol interest groups (alphabetical order) 74
Table G.1 – Device replacement guidelines 75
Table G.2 – Firmware enhancement guidelines 76
Table H.1 – Health status state 78
Table J.1 – Catalog Mapping 83
Table J.2 – Handling of Catalog elements 83
Table L.1 – Elements of ListOfDocumentsMetadataT 87
Table L.2 – Enumerations of DocumentMetadataT 88

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IEC 62769-4:2023
https://standards.iteh.ai/catalog/standards/iec/c90cf594-3e93-4c38-be11-c745c93b3155/iec-62769-4-2023

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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

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This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;

b) moved DocumentClass to Package Documentation Catalog Schema;

c) updated Description of Feature Table updated XML schema for Feature Table.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/857/CDV	65E/914/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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The language used for the development of this International Standard is English.

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INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

1 Scope

This part of IEC 62769 specifies the FDI®[1] Packages. The overall FDI® architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

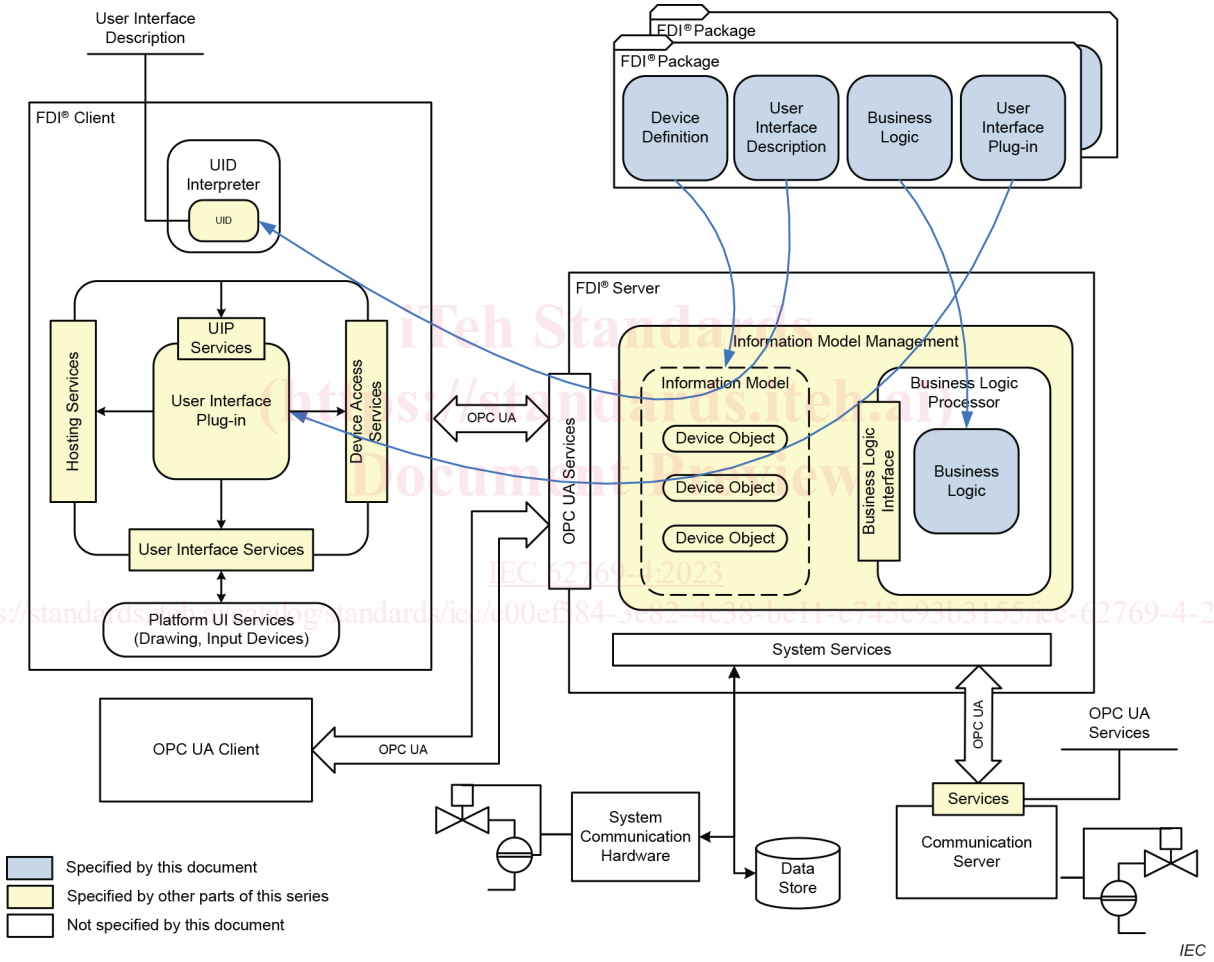

Figure 1 – FDI® architecture diagram

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies.

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[1] FDI® is a registered trademark of the non-profit organization Fieldbus Foundation, Inc. This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

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~~IEC 61804 (all parts), *Function blocks (FB) for process control and electronic device description language (EDDL)*~~

IEC 61804-3, *Devices and integration in enterprise systems − Function blocks (FB) for process control and electronic device description language (EDDL) − Part 3: EDDL syntax and semantics*

IEC 61804-5:~~2015~~2020, *Devices and intergration in enterprise systems − Function blocks (FB) for process control and electronic device description language (EDDL) − Part 5: EDDL Builtin library*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

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IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:~~2016~~2021, ~~*Information technology –*~~ *Document description and processing languages – Office Open XML file formats – Part 2: Open packaging conventions*

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FCG TS10099, *Field Device Integration (FDI®) – Technology Management*

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~~*Extensible Markup Language (XML) 1.0, W3C Recommendation, available at <http://www.w3.org/TR/REC-xml/>*~~

~~*XML Schema Definition Language (XSD) 1.1, W3C Recommendation, available at <http://www.w3.org/TR/xmlschema11-1/>*~~

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ETSI EN 319 132-1, *Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures*

ETSI TS 101 733, *Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAdES)*